

**REMARKS**

The Examiner is thanked for the thorough examination and search of the subject.

Claims 1-11, 13, 15-21, 23-35, 37-44, and 46-50 are pending, wherein claims 1-11, 13, 15-21, 23-35 and 37-44 are currently amended, claims 12, 14, 22, 36 and 45 are canceled, and claims 46-50 are newly added.

It is believed that the newly added claims 46-50 are supported in FIG. 2D within the species applicants elected for response to the Restriction Requirement mailed on Aug. 8, 2005.

**Response to Claim Rejections under 35 U.S.C. 102 and 103**

Applicants respectfully traverse the rejections for at least the reasons set forth below.

**Response to Claims 1-11, 13, 15-21 and 23-26**

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As currently amended, independent claim 1 is recited below:

1. An electronic component comprising:
  - a semiconductor substrate;
  - a metallization structure over said semiconductor substrate;

a passivation layer over said metallization structure, wherein an opening in said passivation layer exposes a top surface of said metallization structure; and  
a patterned circuit layer connected to said top surface, wherein said patterned circuit layer comprises a first portion having a bump formed thereover and a second portion used to be tested thereto.

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*Reconsideration of Claim 1 rejected under 35 U.S.C. 103(a) as being unpatentable by Toyosawa et al (U.S. Patent No. 6,864,562) in view of Kim (U.S. Patent No. 5,854,513) is requested based on the following remarks.*

Applicants respectfully assert that the electronic component claimed in claim 1 patentably distinguishes over Toyosawa et al (U.S. Patent No. 6,864,562) in view of Kim (U.S. Patent No. 5,854,513).

Toyosawa et al teach an electronic component comprising a semiconductor substrate 1, a metallization structure 9a, 9b and 14 over the semiconductor substrate 1, and a passivation layer 15a and 15b over the metallization structure 9a, 9b and 14. An opening in the passivation layer 15a and 15b exposes a top surface of the metallization structure 9a, 9b and 14. ~ See FIG. 1, lines 24-39, col. 6 and lines 45-51, col. 7 ~

Toyosawa et al teach that the electronic component comprises a gold bump 17 connected to the top surface of the metallization structure 9a, 9b and 14. However, Toyosawa et al fail to teach, hint or suggest the subject matter that "a patterned circuit layer connected to the top

surface of the metallization structure 9a, 9b and 14 can comprises a first portion having a bump formed thereover and a second portion used to be tested thereto”.

Kim teaches that an electronic component comprises a patterned circuit layer 22 and 23 comprising a first portion having a bump 27 formed thereover and a second portion used to be tested thereto. The patterned circuit layer 22 and 23 is under a passivation layer 24, multiple openings in the passivation layer 24 exposing the first and second portions of the patterned circuit layer 22 and 23. However, Kim fails to teach, hint or suggest the subject matter that “the patterned circuit layer 22 and 23 can be connected to a top surface of a metallization structure exposed by an opening in the passivation layer 24”.

Applicants consider that claim 1 should be patentable because both Toyosawa et al and Kim fail to teach, hint or suggest the subject matter that “a patterned metal layer comprising a first portion having a bump formed thereover and a second portion used to be tested thereto can be connected to a top surface of a metallization structure exposed by an opening in a passivation layer”.

For at least the foregoing reasons, applicants respectfully submit independent claim 1 patently distinguishes over the prior art references, and should be allowed. For at least the same reasons, dependent claims 2-11, 13, 15-21 and 23-26 patently define over the prior art as well.

**Response to Claims 27-35 and 37-44**

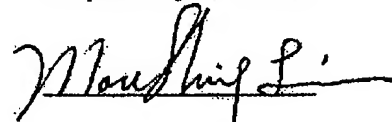
Claims 27-35 and 37-44 have been amended. Reconsiderations for allowable subject matters to claims 27-35 and 37-44 are respectfully requested.

CONCLUSION

Some or all of the pending claims are believed to be in condition for allowance. Accordingly, allowance of the claims and the application as a whole are respectfully requested.

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Respectfully submitted,



Mou-Shiung Lin, CEO  
For and on behalf of MEGIC  
Corporation